

AMENDMENTS TO THE SPECIFICATION:

Please cancel paragraph on page 4, lines 9-16 and replace with the following paragraph:

A1
The wires 37, however, have a lower allowance for a misalignment in arrangement of the terminals and for the ~~un~~uniformity uniformity in the height of the terminals, i.e., for the coplanarity in arrangement of the terminals, compared to the solder balls which allow a relatively large deviation in the arrangement and the height. This lowers the product yield of the electronic devices having such wires 37 irrespective of employing a BGA structure for the electric terminals.

Please cancel paragraph on page 6, lines 12-13 and replace with the following paragraph:

A2
Figs. ~~3A-3C~~ ¹⁰ is are sectional views of an electric terminal according to an embodiment of the present invention.

Please cancel paragraph on page 6, lines 17-18 and replace with the following paragraph:

A3
Figs. 5A and 5B are sectional views showing the electric ~~terminal of Fig. 1~~ terminal of Fig. 3A during a heat cycle test thereof.

[Please add on page 6, lines 19 through 20, the following paragraph:]

Figure 6 is a sectional view showing an electric terminal of the present invention is part of an electronic instrument. ^{as}

Please cancel paragraph on page 8, line ²³₁ through page 9, line 24 and replace with the following paragraph:

At For example, the lead member 13 may be a conductor post disposed on the electronic device 11, or may be a conductor post formed by selectively plating the surface of the electronic device 11. In addition, the lead member 13 may be a conductor post formed separately from the electronic device 11 and then disposed on the electronic device 11, a conductor post formed by etching a metallic film, a conductor post formed by a wire bonding technique, or a metallic wire coated with an insulator film. Further, the lead member 13 may be a conductor bump, at least a portion of which is made of solder, or an insulator post having a central hole filled 28 with a conductor 30 by using, for example, a plating technique.

In the present embodiment, a solder ball is used as the external electrode 12. However, the external electrode 12 may have any structure or any dimensions, so long as the external electrode 12 is bonded to the pad of the printed circuit board by using a thermally melting technique. For example, the external electrode 12 may have a Cu core 18 having a solder coat 20 at least on a portion of the surface thereof. In some cases, solder may be provided onto the printed circuit board or mounting board without providing solder to the external electrode.

The external electrode 12 may have a core ball made of a conductor material or conductor materials and coated with a solder, the core ball having a higher melting point compared to the solder coat. The core ball may be made of a conductor shell receiving therein an insulator sub-core 22.

Please cancel paragraph on page 10, lines 17-22 and replace with the following paragraph:

At The supporting member 14 may include an insulator film or plate having a central

Serial No. 10/002,198
FUS.046

4

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through-hole 28 filled with a conductor plug 30 after the insulator film is attached onto the electronic device. In an alternative, the insulator film or plate of the supporting member 14 may be attached onto the electronic device forming therein the through-hole 28.
